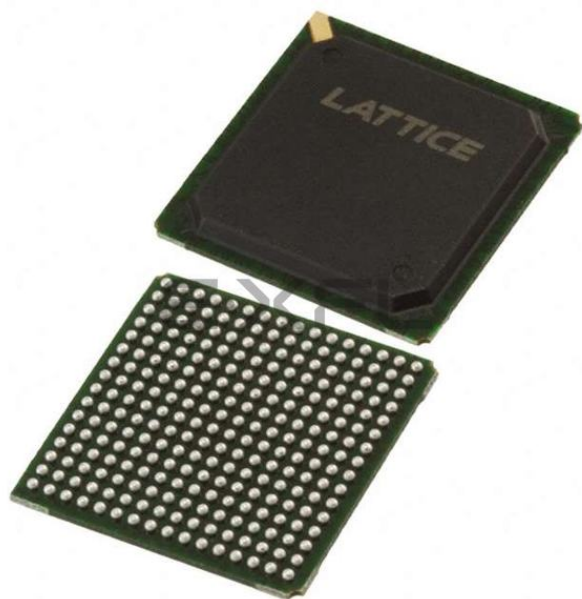




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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

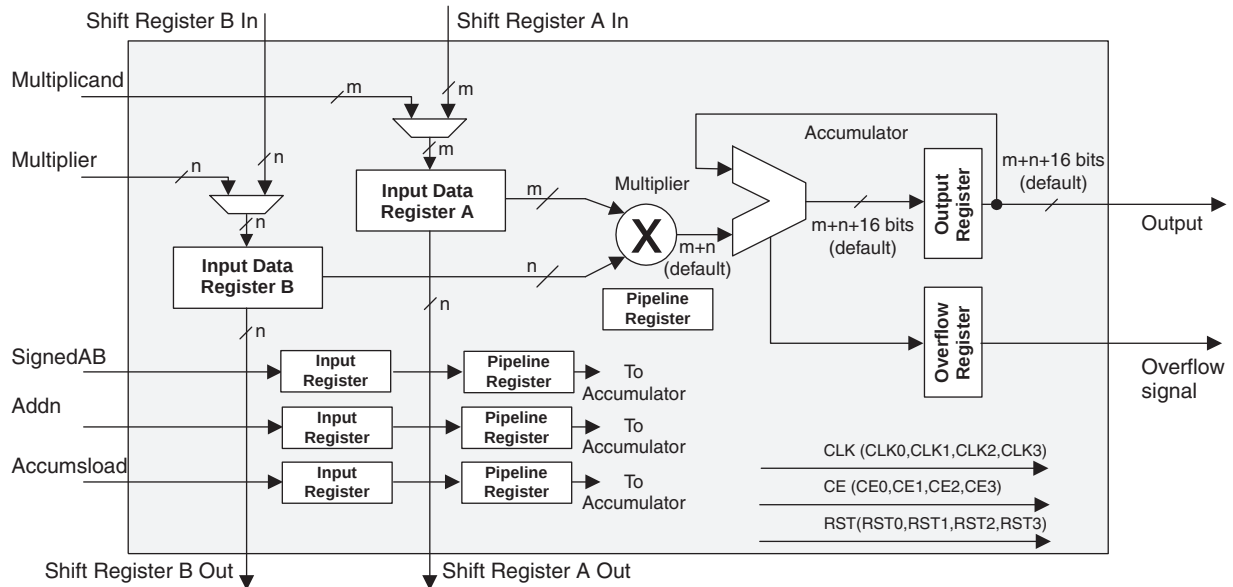
Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	10200
Total RAM Bits	282624
Number of I/O	195
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	256-BGA
Supplier Device Package	256-FPBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfec10e-3f256i

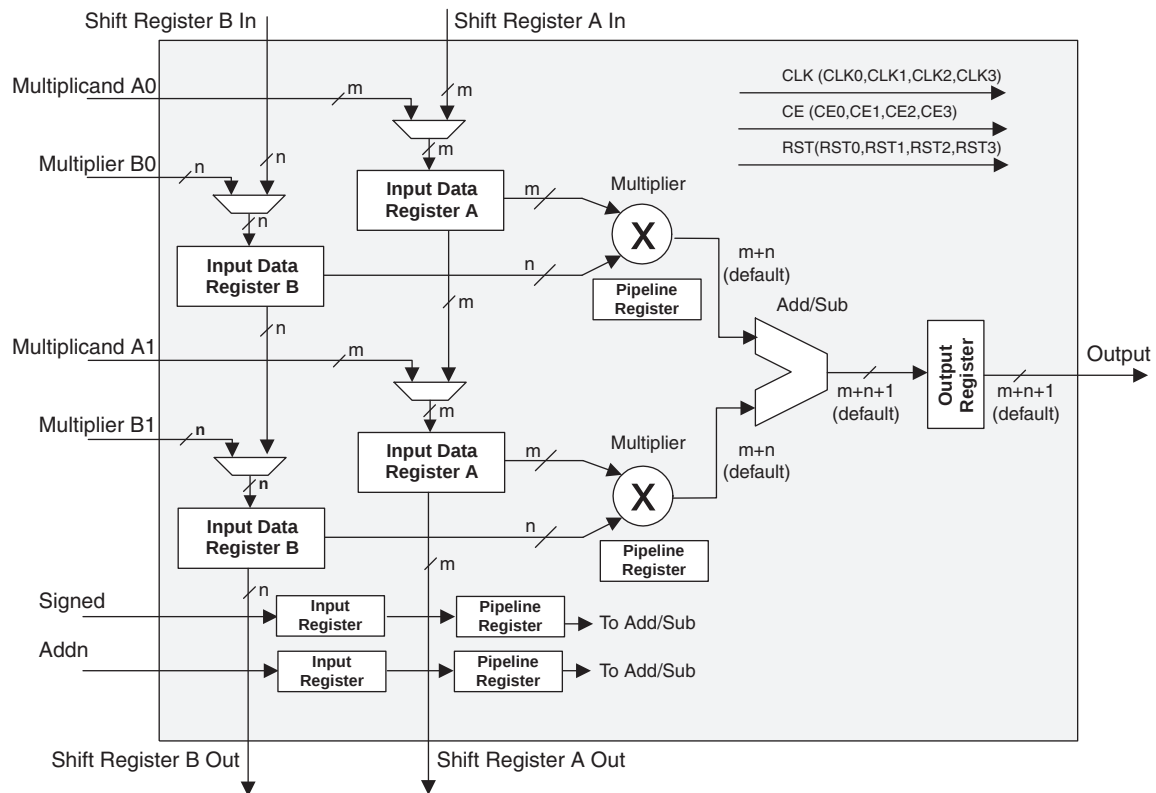
Figure 2-20. MAC sysDSP Element



MULTADD sysDSP Element

In this case, the operands A0 and B0 are multiplied and the result is added/subtracted with the result of the multiplier operation of operands A1 and A2. The user can enable the input, output and pipeline registers. Figure 2-21 shows the MULTADD sysDSP element.

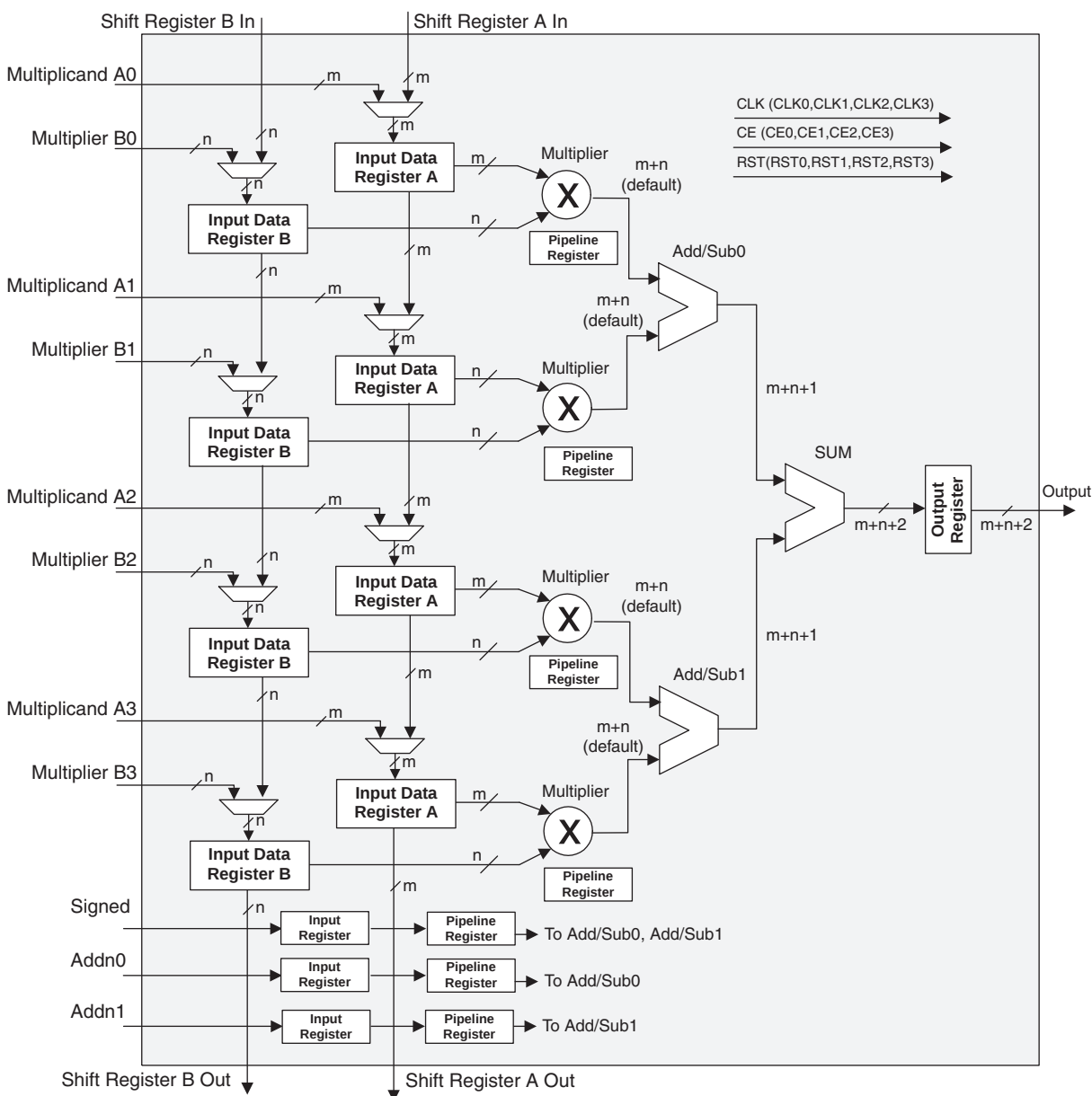
Figure 2-21. MULTADD



MULTADDSUM sysDSP Element

In this case, the operands A0 and B0 are multiplied and the result is added/subtracted with the result of the multiplier operation of operands A1 and B1. Additionally the operands A2 and B2 are multiplied and the result is added/subtracted with the result of the multiplier operation of operands A3 and B3. The result of both addition/subtraction are added in a summation block. The user can enable the input, output and pipeline registers. Figure 2-22 shows the MULTADDSUM sysDSP element.

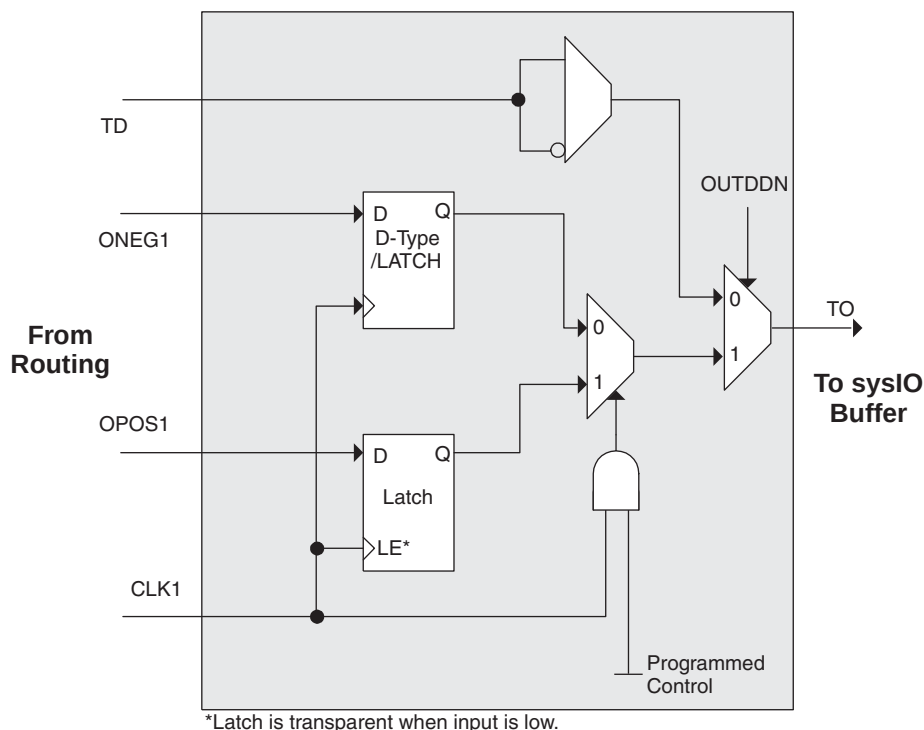
Figure 2-22. MULTADDSUM



Clock, Clock Enable and Reset Resources

Global Clock, Clock Enable and Reset signals from routing are available to every DSP block. Four Clock, Reset and Clock Enable signals are selected for the sysDSP block. From four clock sources (CLK0, CLK1, CLK2, CLK3) one clock is selected for each input register, pipeline register and output register. Similarly Clock enable (CE) and Reset (RST) are selected from their four respective sources (CE0, CE1, CE2, CE3 and RST0, RST1, RST2, RST3) at each input register, pipeline register and output register.

Figure 2-31. Tristate Register Block



Control Logic Block

The control logic block allows the selection and modification of control signals for use in the PIO block. A clock is selected from one of the clock signals provided from the general purpose routing and a DQS signal provided from the programmable DQS pin. The clock can optionally be inverted.

The clock enable and local reset signals are selected from the routing and optionally inverted. The global tristate signal is passed through this block.

DDR Memory Support

Implementing high performance DDR memory interfaces requires dedicated DDR register structures in the input (for read operations) and in the output (for write operations). As indicated in the PIO Logic section, the LatticeEC devices provide this capability. In addition to these registers, the LatticeEC devices contain two elements to simplify the design of input structures for read operations: the DQS delay block and polarity control logic.

DLL Calibrated DQS Delay Block

Source Synchronous interfaces generally require the input clock to be adjusted in order to correctly capture data at the input register. For most interfaces a PLL is used for this adjustment. However in DDR memories the clock (referred to as DQS) is not free running so this approach cannot be used. The DQS Delay block provides the required clock alignment for DDR memory interfaces.

The DQS signal (selected PIOs only) feeds from the PAD through a DQS delay element to a dedicated DQS routing resource. The DQS signal also feeds polarity control logic, which controls the polarity of the clock to the sync registers in the input register blocks. Figures 2-32 and 2-33 show how the DQS transition signals are routed to the PIOs.

The temperature, voltage and process variations of the DQS delay block are compensated by a set of calibration (6-bit bus) signals from two DLLs on opposite sides of the device. Each DLL compensates DQS Delays in its half of the device as shown in Figure 2-33. The DLL loop is compensated for temperature, voltage and process variations by the system clock and feedback loop.

Absolute Maximum Ratings^{1, 2, 3}

Supply Voltage V_{CC}	-0.5 to 1.32V
Supply Voltage V_{CCAUX}	-0.5 to 3.75V
Supply Voltage V_{CCJ}	-0.5 to 3.75V
Output Supply Voltage V_{CCIO}	-0.5 to 3.75V
Dedicated Input Voltage Applied ⁴	-0.5 to 4.25V
I/O Tristate Voltage Applied ⁴	-0.5 to 3.75V
Storage Temperature (Ambient)	-65 to 150°C
Junction Temp. (Tj)	+125°C

1. Stress above those listed under the "Absolute Maximum Ratings" may cause permanent damage to the device. Functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.
2. Compliance with the Lattice *Thermal Management* document is required.
3. All voltages referenced to GND.
4. Overshoot and undershoot of -2V to ($V_{IHMAX} + 2$) volts is permitted for a duration of <20ns.

Recommended Operating Conditions

Symbol	Parameter	Min.	Max.	Units
V_{CC}	Core Supply Voltage	1.14	1.26	V
V_{CCAUX}^3	Auxiliary Supply Voltage	3.135	3.465	V
V_{CCPLL}	PLL Supply Voltage for ECP/EC33	1.14	1.26	V
$V_{CCIO}^{1, 2}$	I/O Driver Supply Voltage	1.140	3.465	V
V_{CCJ}^1	Supply Voltage for IEEE 1149.1 Test Access Port	1.140	3.465	V
t_{JCOM}	Junction Commercial Operation	0	85	°C
t_{JIND}	Junction Industrial Operation	-40	100	°C

1. If V_{CCIO} or V_{CCJ} is set to 1.2V, they must be connected to the same power supply as V_{CC} . If V_{CCIO} or V_{CCJ} is set to 3.3V, they must be connected to the same power supply as V_{CCAUX} .
2. See recommended voltages by I/O standard in subsequent table.
3. V_{CCAUX} ramp rate must not exceed 3mV/ μ s for commercial and 0.6 mV/ μ s for industrial device operations during power up when transitioning between 0.8V and 1.8V.

Hot Socketing Specifications^{1, 2, 3, 4}

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
Top and Bottom General Purpose sysI/Os (Banks 0, 1, 4 and 5), JTAG and Dedicated sysCONFIG Pins						
I_{DK_TB}	Input or I/O Leakage Current	0 δ V_{IN} δ V_{IH} (MAX.)	—	—	+/-1000	μ A
Left and Right General Purpose sysI/Os (Banks 2, 3, 6 and 7)						
I_{DK_LR}	Input or I/O Leakage Current	$V_{IN} \delta V_{CCIO}$	—	—	+/-1000	μ A
		$V_{IN} > V_{CCIO}$	—	35	—	mA

1. Insensitive to sequence of V_{CC} , V_{CCAUX} and V_{CCIO} . However, assumes monotonic rise/fall rates for V_{CC} , V_{CCAUX} and V_{CCIO} .
2. 0 δ $V_{CC} \delta V_{CC}$ (MAX), 0 δ $V_{CCIO} \delta V_{CCIO}$ (MAX) or 0 δ $V_{CCAUX} \delta V_{CCAUX}$ (MAX).
3. I_{DK} is additive to I_{PU} , I_{PW} or I_{BH} .
4. LVCMOS and LVTTL only.

Supply Current (Standby)^{1, 2, 3, 4}

Over Recommended Operating Conditions

Symbol	Parameter	Device	Typ. ⁵	Units
I_{CC}	Core Power Supply Current	LFEC1	6	mA
		LFEC3	10	mA
		LFEC6/LFEC6	15	mA
		LFEC10/LFEC10	25	mA
		LFEC15/LFEC15	35	mA
		LFEC20/LFEC20	60	mA
		LFEC33/LFEC33	85	mA
I_{CCAUX}	Auxiliary Power Supply Current		15	mA
I_{CCPLL}	PLL Power Supply Current		5	mA
I_{CCIO}	Bank Power Supply Current ⁶		2	mA
I_{CCJ}	V_{CCJ} Power Supply Current		5	mA

1. For further information about supply current, please see the list of technical documentation at the end of this data sheet.
2. Assumes all outputs are tristated, all inputs are configured as LVCMOS and held at the V_{CCIO} or GND.
3. Frequency 0MHz.
4. Pattern represents a "blank" configuration data file.
5. $T_J=25^{\circ}\text{C}$, power supplies at nominal voltage.
6. Per bank.

sysI/O Single-Ended DC Electrical Characteristics

Input/Output Standard	V_{IL}		V_{IH}		V_{OL} Max. (V)	V_{OH} Min. (V)	I_{OL}^1 (mA)	I_{OH}^1 (mA)
	Min. (V)	Max. (V)	Min. (V)	Max. (V)				
LVCMOS 3.3	-0.3	0.8	2.0	3.6	0.4	$V_{CCIO} - 0.4$	20, 16, 12, 8, 4	-20, -16, -12, -8, -4
					0.2	$V_{CCIO} - 0.2$	0.1	-0.1
LVTTTL	-0.3	0.8	2.0	3.6	0.4	$V_{CCIO} - 0.4$	20, 16, 12, 8, 4	-20, -16, -12, -8, -4
					0.2	$V_{CCIO} - 0.2$	0.1	-0.1
LVCMOS 2.5	-0.3	0.7	1.7	3.6	0.4	$V_{CCIO} - 0.4$	20, 16, 12, 8, 4	-20, -16, -12, -8, -4
					0.2	$V_{CCIO} - 0.2$	0.1	-0.1
LVCMOS 1.8	-0.3	$0.35V_{CCIO}$	$0.65V_{CCIO}$	3.6	0.4	$V_{CCIO} - 0.4$	16, 12, 8, 4	-16, -12, -8, -4
					0.2	$V_{CCIO} - 0.2$	0.1	-0.1
LVCMOS 1.5	-0.3	$0.35V_{CCIO}$	$0.65V_{CCIO}$	3.6	0.4	$V_{CCIO} - 0.4$	8, 4	-8, -4
					0.2	$V_{CCIO} - 0.2$	0.1	-0.1
LVCMOS 1.2	-0.3	$0.35V_{CC}$	$0.65V_{CC}$	3.6	0.4	$V_{CCIO} - 0.4$	6, 2	-6, -2
					0.2	$V_{CCIO} - 0.2$	0.1	-0.1
PCI	-0.3	$0.3V_{CCIO}$	$0.5V_{CCIO}$	3.6	$0.1V_{CCIO}$	$0.9V_{CCIO}$	1.5	-0.5
SSTL3 class I	-0.3	$V_{REF} - 0.2$	$V_{REF} + 0.2$	3.6	0.7	$V_{CCIO} - 1.1$	8	-8
SSTL3 class II	-0.3	$V_{REF} - 0.2$	$V_{REF} + 0.2$	3.6	0.5	$V_{CCIO} - 0.9$	16	-16
SSTL2 class I	-0.3	$V_{REF} - 0.18$	$V_{REF} + 0.18$	3.6	0.54	$V_{CCIO} - 0.62$	7.6	-7.6
SSTL2 class II	-0.3	$V_{REF} - 0.18$	$V_{REF} + 0.18$	3.6	0.35	$V_{CCIO} - 0.43$	15.2	-15.2
SSTL18 class I	-0.3	$V_{REF} - 0.125$	$V_{REF} + 0.125$	3.6	0.4	$V_{CCIO} - 0.4$	6.7	-6.7
HSTL15 class I	-0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	3.6	0.4	$V_{CCIO} - 0.4$	8	-8
HSTL15 class III	-0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	3.6	0.4	$V_{CCIO} - 0.4$	24	-8
HSTL18 class I	-0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	3.6	0.4	$V_{CCIO} - 0.4$	9.6	-9.6
HSTL18 class II	-0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	3.6	0.4	$V_{CCIO} - 0.4$	16	-16
HSTL18 class III	-0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	3.6	0.4	$V_{CCIO} - 0.4$	24	-8

1. The average DC current drawn by I/Os between GND connections, or between the last GND in an I/O bank and the end of an I/O bank, as shown in the logic signal connections table shall not exceed $n * 8\text{mA}$. Where n is the number of I/Os between bank GND connections or between the last GND in a bank and the end of a bank.

sysI/O Differential Electrical Characteristics

LVDS

Over Recommended Operating Conditions

Parameter Symbol	Parameter Description	Test Conditions	Min.	Typ.	Max.	Units
V_{INP}, V_{INM}	Input voltage		0	—	2.4	V
V_{THD}	Differential input threshold		+/-100	—	—	mV
V_{CM}	Input common mode voltage	100mV δV_{THD}	$V_{THD}/2$	1.2	1.8	V
		200mV δV_{THD}	$V_{THD}/2$	1.2	1.9	V
		350mV δV_{THD}	$V_{THD}/2$	1.2	2.0	V
I_{IN}	Input current	Power on or power off	—	—	+/-10	μA
V_{OH}	Output high voltage for V_{OP} or V_{OM}	$R_T = 100 \text{ Ohm}$	—	1.38	1.60	V
V_{OL}	Output low voltage for V_{OP} or V_{OM}	$R_T = 100 \text{ Ohm}$	0.9V	1.03	—	V
V_{OD}	Output voltage differential	$(V_{OP} - V_{OM}), R_T = 100 \text{ Ohm}$	250	350	450	mV
ΔV_{OD}	Change in V_{OD} between high and low		—	—	50	mV
V_{OS}	Output voltage offset	$(V_{OP} + V_{OM})/2, R_T = 100 \text{ Ohm}$	1.125	1.25	1.375	V
ΔV_{OS}	Change in V_{OS} between H and L		—	—	50	mV
I_{OSD}	Output short circuit current	$V_{OD} = 0V$ Driver outputs shorted	—	—	6	mA

Differential HSTL and SSTL

Differential HSTL and SSTL outputs are implemented as a pair of complementary single-ended outputs. All allowable single-ended output classes (class I and class II) are supported in this mode.

LVDS25E

The top and bottom side of LatticeECP/EC devices support LVDS outputs via emulated complementary LVCMOS outputs in conjunction with a parallel resistor across the driver outputs. The scheme shown in

Figure 3-1 is one possible solution for point-to-point signals.

Figure 3-1. LVDS25E Output Termination Example

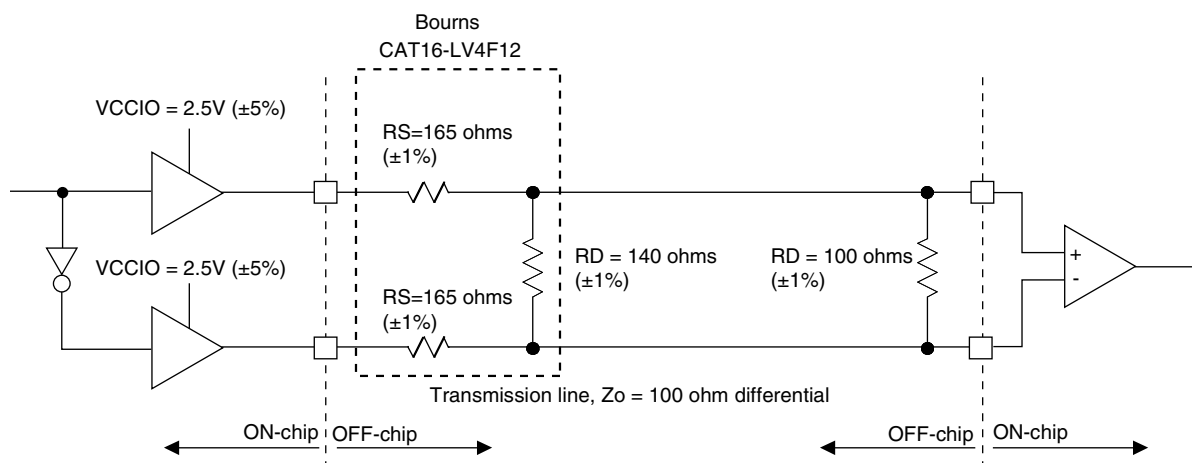


Table 3-1. LVDS25E DC Conditions

Parameter	Description	Typical	Units
V_{OH}	Output high voltage	1.42	V
V_{OL}	Output low voltage	1.08	V
V_{OD}	Output differential voltage	0.35	V
V_{CM}	Output common mode voltage	1.25	V
Z_{BACK}	Back impedance	100	$\%$

LatticeECP/EC External Switching Characteristics (Continued)

Over Recommended Operating Conditions

Parameter	Description	Device	-5		-4		-3		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
t_{DQVBS}	Data Valid Before DQS	All	0.20	—	0.20	—	0.20	—	UI
t_{DQVAS}	Data Valid After DQS	All	0.20	—	0.20	—	0.20	—	UI
f_{MAX_DDR}	DDR Clock Frequency	All	95	200	95	166	95	133	MHz
Primary and Secondary Clock⁶									
$f_{MAX_PRI}^2$	Frequency for Primary Clock Tree	All	—	420	—	378	—	340	MHz
t_{W_PRI}	Clock Pulse Width for Primary Clock	All	1.19	—	1.19	—	1.19	—	ns
t_{SKEW_PRI}	Primary Clock Skew within an I/O Bank	All	—	250	—	300	—	350	ps

1. General timing numbers based on LVCMOS2.5V, 12 mA. Loading of 0 pF.

2. Using LVDS I/O standard.

3. DDR timing numbers based on SSTL I/O.

4. DDR specifications are characterized but not tested.

5. UI is average bit period.

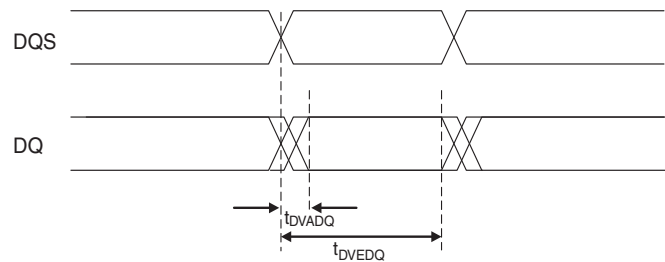
6. Based on a single primary clock.

7. These timing numbers were generated using ispLEVER design tool. Exact performance may vary with design and tool version. The tool uses internal parameters that have been characterized but are not tested on every device.

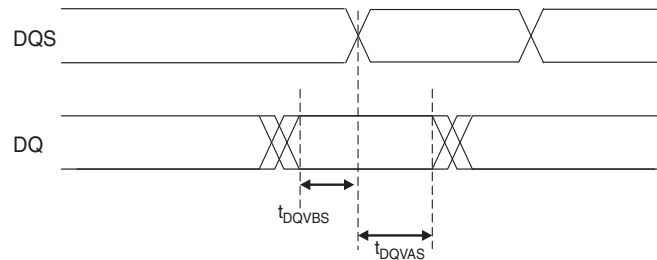
Timing v.G 0.30

Figure 3-5. DDR Timings

DQ and DQS Read Timings



DQ and DQS Write Timings



LatticeECP/EC Internal Switching Characteristics (Continued)

Over Recommended Operating Conditions

Parameter	Description	-5		-4		-3		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
t_{SUC_EBR}	Clock Enable Setup Time to EBR Output Register	0.18	—	0.21	—	0.25	—	ns
t_{HCE_EBR}	Clock Enable Hold Time to EBR Output Register	-0.14	—	-0.17	—	-0.20	—	ns
t_{RSTO_EBR}	Reset To Output Delay Time from EBR Output Register	—	1.47	—	1.76	—	2.05	ns
PLL Parameters								
t_{RSTREC}	Reset Recovery to Rising Clock	1.00	—	1.00	—	1.00	—	ns
t_{RSTSU}	Reset Signal Setup Time	1.00	—	1.00	—	1.00	—	ns
DSP Block Timing^{2,3}								
t_{SUI_DSP}	Input Register Setup Time	-0.38	—	-0.30	—	-0.23	—	ns
t_{HI_DSP}	Input Register Hold Time	0.71	—	0.86	—	1.00	—	ns
t_{SUP_DSP}	Pipeline Register Setup Time	3.31	—	3.98	—	4.64	—	ns
t_{HP_DSP}	Pipeline Register Hold Time	0.71	—	0.86	—	1.00	—	ns
$t_{SUO_DSP}^4$	Output Register Setup Time	5.54	—	6.64	—	7.75	—	ns
$t_{HO_DSP}^4$	Output Register Hold Time	0.71	—	0.86	—	1.00	—	ns
$t_{COI_DSP}^4$	Input Register Clock to Output Time	—	7.50	—	9.00	—	10.50	ns
$t_{COP_DSP}^4$	Pipeline Register Clock to Output Time	—	4.66	—	5.60	—	6.53	ns
t_{COO_DSP}	Output Register Clock to Output Time	—	1.47	—	1.77	—	2.06	ns
$t_{SUADSUB}$	AdSub Input Register Setup Time	-0.38	—	-0.30	—	-0.23	—	ns
t_{HADSUB}	AdSub Input Register Hold Time	0.71	—	0.86	—	1.00	—	ns

1. Internal parameters are characterized but not tested on every device.

2. These parameters apply to LatticeECP devices only.

3. DSP Block is configured in Multiply Add/Sub 18 x 18 Mode.

4. These parameters include the Adder Subtractor block in the path.

Timing v.G 0.30

LatticeECP/EC Family Timing Adders^{1, 2, 3}
Over Recommended Operating Conditions

Buffer Type	Description	-5	-4	-3	Units
Input Adjusters					
LVDS25	LVDS	0.41	0.50	0.58	ns
BLVDS25	BLVDS	0.41	0.50	0.58	ns
LVPECL33	LVPECL	0.50	0.60	0.70	ns
HSTL18_I	HSTL_18 class I	0.41	0.49	0.57	ns
HSTL18_II	HSTL_18 class II	0.41	0.49	0.57	ns
HSTL18_III	HSTL_18 class III	0.41	0.49	0.57	ns
HSTL18D_I	Differential HSTL 18 class I	0.37	0.44	0.52	ns
HSTL18D_II	Differential HSTL 18 class II	0.37	0.44	0.52	ns
HSTL18D_III	Differential HSTL 18 class III	0.37	0.44	0.52	ns
HSTL15_I	HSTL_15 class I	0.40	0.48	0.56	ns
HSTL15_III	HSTL_15 class III	0.40	0.48	0.56	ns
HSTL15D_I	Differential HSTL 15 class I	0.37	0.44	0.51	ns
HSTL15D_III	Differential HSTL 15 class III	0.37	0.44	0.51	ns
SSTL33_I	SSTL_3 class I	0.46	0.55	0.64	ns
SSTL33_II	SSTL_3 class II	0.46	0.55	0.64	ns
SSTL33D_I	Differential SSTL_3 class I	0.39	0.47	0.55	ns
SSTL33D_II	Differential SSTL_3 class II	0.39	0.47	0.55	ns
SSTL25_I	SSTL_2 class I	0.43	0.51	0.60	ns
SSTL25_II	SSTL_2 class II	0.43	0.51	0.60	ns
SSTL25D_I	Differential SSTL_2 class I	0.38	0.45	0.53	ns
SSTL25D_II	Differential SSTL_2 class II	0.38	0.45	0.53	ns
SSTL18_I	SSTL_18 class I	0.40	0.48	0.56	ns
SSTL18D_I	Differential SSTL_18 class I	0.37	0.44	0.51	ns
LVTTL33	LVTTL	0.07	0.09	0.10	ns
LVC MOS33	LVC MOS 3.3	0.07	0.09	0.10	ns
LVC MOS25	LVC MOS 2.5	0.00	0.00	0.00	ns
LVC MOS18	LVC MOS 1.8	0.07	0.09	0.10	ns
LVC MOS15	LVC MOS 1.5	0.24	0.29	0.33	ns
LVC MOS12	LVC MOS 1.2	1.27	1.52	1.77	ns
PCI33	PCI	0.07	0.09	0.10	ns
Output Adjusters					
LVDS25E	LVDS 2.5 E	0.12	0.14	0.17	ns
LVDS25	LVDS 2.5	-0.44	-0.53	-0.62	ns
BLVDS25	BLVDS 2.5	0.33	0.40	0.46	ns
LVPECL33	LVPECL 3.3	0.20	0.24	0.28	ns
HSTL18_I	HSTL_18 class I	-0.10	-0.12	-0.14	ns
HSTL18_II	HSTL_18 class II	0.06	0.07	0.08	ns
HSTL18_III	HSTL_18 class III	0.15	0.19	0.22	ns
HSTL18D_I	Differential HSTL 18 class I	-0.10	-0.12	-0.14	ns
HSTL18D_II	Differential HSTL 18 class II	0.06	0.07	0.08	ns
HSTL18D_III	Differential HSTL 18 class III	0.15	0.19	0.22	ns
HSTL15_I	HSTL_15 class I	0.08	0.10	0.11	ns

Signal Descriptions

Signal Name	I/O	Description
General Purpose		
P[Edge] [Row/Column Number*]_[A/B]	I/O	[Edge] indicates the edge of the device on which the pad is located. Valid edge designations are L (Left), B (Bottom), R (Right), T (Top). [Row/Column Number] indicates the PFU row or the column of the device on which the PIC exists. When Edge is T (Top) or (Bottom), only need to specify Row Number. When Edge is L (Left) or R (Right), only need to specify Column Number. [A/B] indicates the PIO within the PIC to which the pad is connected. Some of these user-programmable pins are shared with special function pins. These pin when not used as special purpose pins can be programmed as I/Os for user logic. During configuration the user-programmable I/Os are tri-stated with an internal pull-up resistor enabled. If any pin is not used (or not bonded to a package pin), it is also tri-stated with an internal pull-up resistor enabled after configuration.
GSRN	I	Global RESET signal (active low). Any I/O pin can be GSRN.
NC	—	No connect.
GND	—	Ground. Dedicated pins.
V _{CC}	—	Power supply pins for core logic. Dedicated pins.
V _{CCAUX}	—	Auxiliary power supply pin. It powers all the differential and referenced input buffers. Dedicated pins.
V _{CCIOx}	—	Power supply pins for I/O bank x. Dedicated pins.
V _{REF1_x} , V _{REF2_x}	—	Reference supply pins for I/O bank x. Pre-determined pins in each bank are assigned as V _{REF} inputs. When not used, they may be used as I/O pins.
XRES	—	10K ohm +/-1% resistor must be connected between this pad and ground.
V _{CCPLL}	—	Power supply pin for PLL. Applicable to ECP/EC33 device.
PLL and Clock Functions (Used as user programmable I/O pins when not in use for PLL or clock pins)		
[LOC][num]_PLL[T, C]_IN_A	I	Reference clock (PLL) input pads: ULM, LLM, URM, LRM, num = row from center, T = true and C = complement, index A,B,C...at each side.
[LOC][num]_PLL[T, C]_FB_A	I	Optional feedback (PLL) input pads: ULM, LLM, URM, LRM, num = row from center, T = true and C = complement, index A,B,C...at each side.
PCLK[T, C]_[n:0]_[3:0]	I	Primary Clock pads, T = true and C = complement, n per side, indexed by bank and 0,1,2,3 within bank.
[LOC]DQS[num]	I	DQS input pads: T (Top), R (Right), B (Bottom), L (Left), DQS, num = ball function number. Any pad can be configured to be output.
Test and Programming (Dedicated pins)		
TMS	I	Test Mode Select input, used to control the 1149.1 state machine. Pull-up is enabled during configuration.
TCK	I	Test Clock input pin, used to clock the 1149.1 state machine. No pull-up enabled.

Power Supply and NC Connections

Signals	100 TQFP	144 TQFP	208 PQFP	256 fpBGA
VCC	12, 64	EC1, EC3: 13, 92, 99 ECP/EC6: 11, 13, 92, 99	EC1, EC3: 26, 128, 135 ECP/EC6: 24, 26, 128, 135 ECP/EC10: 5, 24, 26, 128, 135, 152	E12, E5, E8, M12, M5, M9, F6, F11, L11, L6
VCCIO0	100	136, 143	EC1: 187, 208 EC3, ECP/EC6, ECP/EC10: 187, 197, 208	F7, F8
VCCIO1	86	110, 125	157, 176	F9, F10
VCCIO2	73	108	EC1: 155 EC3, ECP/EC6, ECP/EC10: 145, 155	G11, H11
VCCIO3	56	73, 84	106, 120	J11, K11
VCCIO4	38	55, 71	85, 104	L9, L10
VCCIO5	26	38, 44	EC1: 53, 74 EC2, ECP/EC6, ECP/EC10: 53, 64, 74	L7, L8
VCCIO6	24	24, 36	37, 51	J6, K6
VCCIO7	2	1	EC1: 2 EC3, ECP/EC6, ECP/EC10: 2, 13	G6, H6
VCCJ	18	19	32	L4
VCCAUX	37, 87	54, 126	EC1: 84, 177 EC3, ECP/EC6, ECP/EC10: 22, 84, 136, 177	B15, R2
VCCPLL	—	—	—	—
GND, GND0-GND7	1, 14, 25, 35, 51, 68, 74, 89	EC1, EC3: 15, 28, 37, 52, 63, 72, 80, 96, 98, 109, 117, 128, 144 ECP/EC6: 12, 15, 28, 37, 52, 63, 72, 80, 96, 98, 109, 117, 128, 144	EC1: 1, 28, 41, 52, 82, 93, 105, 116, 132, 134, 156, 168, 179 EC3: 1, 28, 41, 52, 72, 82, 93, 105, 116, 132, 134, 138, 156, 168, 179, 189 ECP/EC6: 1, 18, 25, 28, 41, 52, 72, 82, 93, 105, 116, 132, 134, 138, 156, 168, 179, 189 ECP/EC10: 1, 6, 18, 25, 28, 41, 52, 72, 82, 93, 105, 116, 132, 134, 138, 151, 156, 168, 179, 189	A1, A16, G10, G7, G8, G9, H10, H7, H8, H9, J10, J7, J8, J9, K10, K7, K8, K9, T1, T16
NC	—	EC1, EC3: 11, 12 ECP6/EC6: None	EC1: 5, 6, 7, 8, 9, 10, 11, 12, 13, 14, 18, 22, 24, 25, 54, 55, 56, 57, 58, 59, 60, 61, 62, 63, 64, 72, 103, 136, 138, 144, 145, 146, 147, 148, 149, 150, 151, 152, 158, 189, 197, 198, 199, 200, 201, 202, 203, 204, 205, 206, 207 EC3: 5, 6, 18, 24, 25, 103, 151, 152, 158 ECP/EC6: 5, 6, 151, 152 ECP/EC10: None	EC3: G5, H5, F2, F1, H4, H3, G2, G1, J4, J3, J5, K5, H2, H1, J2, J1, R12, H16, H15, G16, G15, K12, J12, J14, J15, F16, F15, J13, H13, H14, G14, E16, E15, B13, C13 ECP/EC10: None ECP/EC15: None

LFEC6P/EC6, LFEC6P/EC10 Logic Signal Connections: 208 PQFP (Cont.)

Pin Number	LFEC6P/EC6				LFEC6P/EC10			
	Pin Function	Bank	LVDS	Dual Function	Pin Function	Bank	LVDS	Dual Function
127	CFG0	3			CFG0	3		
128	VCC	-			VCC	-		
129	PROGRAMN	3			PROGRAMN	3		
130	CCLK	3			CCLK	3		
131	INITN	3			INITN	3		
132	GND	-			GND	-		
133	DONE	3			DONE	3		
134	GND	-			GND	-		
135	VCC	-			VCC	-		
136	VCCAUX	-			VCCAUX	-		
137	PR9B	2	C	PCLKC2_0	PR18B	2	C	PCLKC2_0
138	GND2	2			GND2	2		
139	PR9A	2	T	PCLKT2_0	PR18A	2	T	PCLKT2_0
140	PR8B	2	C		PR17B	2	C	
141	PR8A	2	T		PR17A	2	T	
142	PR7B	2	C		PR16B	2	C	
143	PR7A	2	T		PR16A	2	T	
144	PR6B	2	C		PR15B	2	C	
145	VCCIO2	2			VCCIO2	2		
146	PR6A	2	T	RDQS6	PR15A	2	T	RDQS15
147	PR5B	2	C		PR14B	2	C	
148	PR5A	2	T		PR14A	2	T	
149	PR4B	2	C		PR13B	2	C	
150	PR4A	2	T		PR13A	2	T	
151	NC	-			GND	-		
152	NC	-			VCC	-		
153	PR2B	2	C	VREF1_2	PR2B	2	C	VREF1_2
154	PR2A	2	T	VREF2_2	PR2A	2	T	VREF2_2
155	VCCIO2	2			VCCIO2	2		
156*	GND1 GND2	-			GND1 GND2	-		
157	VCCIO1	1			VCCIO1	1		
158	PT33A	1			PT41A	1		
159	PT25B	1	C		PT33B	1	C	
160	PT25A	1	T		PT33A	1	T	
161	PT24B	1	C		PT32B	1	C	
162	PT24A	1	T		PT32A	1	T	
163	PT23B	1	C		PT31B	1	C	
164	PT23A	1	T		PT31A	1	T	
165	PT22B	1	C		PT30B	1	C	
166	PT22A	1	T	TDQS22	PT30A	1	T	TDQS30
167	PT21B	1	C		PT29B	1	C	
168	GND1	1			GND1	1		

LFEC6/EC6, LFEC6/EC10, LFEC6/EC15 Logic Signal Connections: 484 fpBGA (Cont.)

LFEC6/LFEC6					LFEC10/LFEC10					LFEC6/LFEC15				
Ball Number	Ball Function	Bank	LVDS	Dual Function	Ball Number	Ball Function	Bank	LVDS	Dual Function	Ball Number	Ball Function	Bank	LVDS	Dual Function
M4	PL13A	6	T		M4	PL22A	6	T		M4	PL26A	6	T	
M5	PL13B	6	C		M5	PL22B	6	C		M5	PL26B	6	C	
M1	PL14A	6	T		M1	PL23A	6	T		M1	PL27A	6	T	
GND	GND6	6			GND	GND6	6			GND	GND6	6		
M2	PL14B	6	C		M2	PL23B	6	C		M2	PL27B	6	C	
N3	PL15A	6	T	LDQS15	N3	PL24A	6	T	LDQS24	N3	PL28A	6	T	LDQS28
M3	PL15B	6	C		M3	PL24B	6	C		M3	PL28B	6	C	
N5	PL16A	6	T		N5	PL25A	6	T		N5	PL29A	6	T	
N4	PL16B	6	C		N4	PL25B	6	C		N4	PL29B	6	C	
N1	PL17A	6	T		N1	PL26A	6	T		N1	PL30A	6	T	
N2	PL17B	6	C		N2	PL26B	6	C		N2	PL30B	6	C	
P1	PL18A	6	T		P1	PL27A	6	T		P1	PL31A	6	T	
GND	GND6	6			GND	GND6	6			GND	GND6	6		
P2	PL18B	6	C		P2	PL27B	6	C		P2	PL31B	6	C	
R6	NC	-			R6	NC	-			R6	PL32A	6	T	
P5	NC	-			P5	NC	-			P5	PL32B	6	C	
P3	NC	-			P3	NC	-			P3	PL33A	6	T	
P4	NC	-			P4	NC	-			P4	PL33B	6	C	
R1	NC	-			R1	NC	-			R1	PL34A	6	T	
R2	NC	-			R2	NC	-			R2	PL34B	6	C	
R5	NC	-			R5	NC	-			R5	PL35A	6	T	
GND	-	-			-	-	-			GND	GND6	6		
R4	NC	-			R4	NC	-			R4	PL35B	6	C	
T1	NC	-			T1	NC	-			T1	NC	-		
T2	NC	-			T2	NC	-			T2	NC	-		
R3	NC	-			R3	NC	-			R3	NC	-		
T3	NC	-			T3	NC	-			T3	NC	-		
T5	TCK	6			T5	TCK	6			T5	TCK	6		
U5	TDI	6			U5	TDI	6			U5	TDI	6		
T4	TMS	6			T4	TMS	6			T4	TMS	6		
U1	TDO	6			U1	TDO	6			U1	TDO	6		
U2	VCCJ	6			U2	VCCJ	6			U2	VCCJ	6		
V1	PL20A	6	T	LLM0_PLLT_IN_A	V1	PL29A	6	T	LLM0_PLLT_IN_A	V1	PL37A	6	T	LLM0_PLLT_IN_A
V2	PL20B	6	C	LLM0_PLLC_IN_A	V2	PL29B	6	C	LLM0_PLLC_IN_A	V2	PL37B	6	C	LLM0_PLLC_IN_A
U3	PL21A	6	T	LLM0_PLLT_FB_A	U3	PL30A	6	T	LLM0_PLLT_FB_A	U3	PL38A	6	T	LLM0_PLLT_FB_A
V3	PL21B	6	C	LLM0_PLLC_FB_A	V3	PL30B	6	C	LLM0_PLLC_FB_A	V3	PL38B	6	C	LLM0_PLLC_FB_A
U4	PL22A	6	T		U4	PL31A	6	T		U4	PL39A	6	T	
V5	PL22B	6	C		V5	PL31B	6	C		V5	PL39B	6	C	
W1	PL23A	6	T		W1	PL32A	6	T		W1	PL40A	6	T	
GND	GND6	6			GND	GND6	6			GND	GND6	6		
W2	PL23B	6	C		W2	PL32B	6	C		W2	PL40B	6	C	
Y1	PL24A	6	T	LDQS24	Y1	PL33A	6	T	LDQS33	Y1	PL41A	6	T	LDQS41
Y2	PL24B	6	C		Y2	PL33B	6	C		Y2	PL41B	6	C	
AA1	PL25A	6	T		AA1	PL34A	6	T		AA1	PL42A	6	T	
AA2	PL25B	6	C		AA2	PL34B	6	C		AA2	PL42B	6	C	
W4	PL26A	6	T		W4	PL35A	6	T		W4	PL43A	6	T	
V4	PL26B	6	C		V4	PL35B	6	C		V4	PL43B	6	C	
W3	PL27A	6	T	VREF1_6	W3	PL36A	6	T	VREF1_6	W3	PL44A	6	T	VREF1_6
Y3	PL27B	6	C	VREF2_6	Y3	PL36B	6	C	VREF2_6	Y3	PL44B	6	C	VREF2_6
GND	GND6	6			GND	GND6	6			GND	GND6	6		

LFEC20/EC20 and LFEC20/EC33 Logic Signal Connections: 484 fpBGA (Cont.)

LFEC20/LFEC20					LFEC20/LFEC33				
Ball Number	Ball Function	Bank	LVD S	Dual Function	Ball Number	Ball Function	Bank	LVD S	Dual Function
A7	PT27B	0	C		A7	PT27B	0	C	
A6	PT27A	0	T		A6	PT27A	0	T	
B7	PT26B	0	C		B7	PT26B	0	C	
B8	PT26A	0	T		B8	PT26A	0	T	
A5	PT25B	0	C		A5	PT25B	0	C	
GND	GND0	0			GND	GND0	0		
B6	PT25A	0	T		B6	PT25A	0	T	
G10	PT24B	0	C		G10	PT24B	0	C	
E10	PT24A	0	T		E10	PT24A	0	T	
F10	PT23B	0	C		F10	PT23B	0	C	
D10	PT23A	0	T		D10	PT23A	0	T	
G9	PT22B	0	C		G9	PT22B	0	C	
E9	PT22A	0	T	TDQS22	E9	PT22A	0	T	TDQS22
C9	PT21B	0	C		C9	PT21B	0	C	
GND	GND0	0			GND	GND0	0		
C8	PT21A	0	T		C8	PT21A	0	T	
F9	PT20B	0	C		F9	PT20B	0	C	
D9	PT20A	0	T		D9	PT20A	0	T	
F8	PT19B	0	C		F8	PT19B	0	C	
D7	PT19A	0	T		D7	PT19A	0	T	
D8	PT18B	0	C		D8	PT18B	0	C	
C7	PT18A	0	T		C7	PT18A	0	T	
GND	GND0	0			GND	GND0	0		
A4	PT17B	0	C		A4	PT17B	0	C	
B4	PT17A	0	T		B4	PT17A	0	T	
C4	PT16B	0	C		C4	PT16B	0	C	
C5	PT16A	0	T		C5	PT16A	0	T	
D6	PT15B	0	C		D6	PT15B	0	C	
B5	PT15A	0	T		B5	PT15A	0	T	
E6	PT14B	0	C		E6	PT14B	0	C	
C6	PT14A	0	T	TDQS14	C6	PT14A	0	T	TDQS14
A3	PT13B	0	C		A3	PT13B	0	C	
GND	GND0	0			GND	GND0	0		
B3	PT13A	0	T		B3	PT13A	0	T	
F6	PT12B	0	C		F6	PT12B	0	C	
D5	PT12A	0	T		D5	PT12A	0	T	
F7	PT11B	0	C		F7	PT11B	0	C	
E8	PT11A	0	T		E8	PT11A	0	T	
G6	PT10B	0	C		G6	PT10B	0	C	
E7	PT10A	0	T		E7	PT10A	0	T	
GND	GND0	0			GND	GND0	0		
GND	GND0	0			GND	GND0	0		
A1	GND	-			A1	GND	-		
A22	GND	-			A22	GND	-		

LFECP/EC20, LFECP/EC33 Logic Signal Connections: 672 fpBGA (Cont.)

LFEC20/LFECP20					LFECP/EC33				
Ball Number	Ball Function	Bank	LVDS	Dual Function	Ball Number	Ball Function	Bank	LVDS	Dual Function
A5	PT13B	0	C		A5	PT13B	0	C	
GND	GND0	0			GND	GND0	0		
A4	PT13A	0	T		A4	PT13A	0	T	
F9	PT12B	0	C		F9	PT12B	0	C	
B6	PT12A	0	T		B6	PT12A	0	T	
E9	PT11B	0	C		E9	PT11B	0	C	
C8	PT11A	0	T		C8	PT11A	0	T	
G8	PT10B	0	C		G8	PT10B	0	C	
B5	PT10A	0	T		B5	PT10A	0	T	
A3	PT9B	0	C		A3	PT9B	0	C	
GND	GND0	0			GND	GND0	0		
A2	PT9A	0	T		A2	PT9A	0	T	
F8	PT8B	0	C		F8	PT8B	0	C	
B4	PT8A	0	T		B4	PT8A	0	T	
E8	PT7B	0	C		E8	PT7B	0	C	
B3	PT7A	0	T		B3	PT7A	0	T	
D8	PT6B	0	C		D8	PT6B	0	C	
G7	PT6A	0	T	TDQS6	G7	PT6A	0	T	TDQS6
C4	PT5B	0	C		C4	PT5B	0	C	
C5	PT5A	0	T		C5	PT5A	0	T	
E7	PT4B	0	C		E7	PT4B	0	C	
D4	PT4A	0	T		D4	PT4A	0	T	
F7	PT3B	0	C		F7	PT3B	0	C	
D6	PT3A	0	T		D6	PT3A	0	T	
D7	PT2B	0	C		D7	PT2B	0	C	
E6	PT2A	0	T		E6	PT2A	0	T	
GND	GND0	0			GND	GND0	0		
K10	GND	-			K10	GND	-		
K11	GND	-			K11	GND	-		
K12	GND	-			K12	GND	-		
K13	GND	-			K13	GND	-		
K14	GND	-			K14	GND	-		
K15	GND	-			K15	GND	-		
K16	GND	-			K16	GND	-		
L10	GND	-			L10	GND	-		
L11	GND	-			L11	GND	-		
L12	GND	-			L12	GND	-		
L13	GND	-			L13	GND	-		
L14	GND	-			L14	GND	-		
L15	GND	-			L15	GND	-		
L16	GND	-			L16	GND	-		
L17	GND	-			L17	GND	-		

LFECP/EC20, LFECP/EC33 Logic Signal Connections: 672 fpBGA (Cont.)

LFEC20/LFECP20					LFECP/EC33				
Ball Number	Ball Function	Bank	LVDS	Dual Function	Ball Number	Ball Function	Bank	LVDS	Dual Function
U12	GND	-			U12	GND	-		
U13	GND	-			U13	GND	-		
U14	GND	-			U14	GND	-		
U15	GND	-			U15	GND	-		
U16	GND	-			U16	GND	-		
U17	GND	-			U17	GND	-		
H10	VCC	-			H10	VCC	-		
H11	VCC	-			H11	VCC	-		
H16	VCC	-			H16	VCC	-		
H17	VCC	-			H17	VCC	-		
H18	VCC	-			H18	VCC	-		
H19	VCC	-			H19	VCC	-		
H8	VCC	-			H8	VCC	-		
H9	VCC	-			H9	VCC	-		
J18	VCC	-			J18	VCC	-		
J9	VCC	-			J9	VCC	-		
K8	VCC	-			K8	VCC	-		
L19	VCC	-			L19	VCC	-		
M19	VCC	-			M19	VCC	-		
N7	VCC	-			N7	VCC	-		
R20	VCC	-			R20	VCC	-		
R7	VCC	-			R7	VCC	-		
T19	VCC	-			T19	VCC	-		
V18	VCC	-			V18	VCC	-		
V8	VCC	-			V8	VCC	-		
V9	VCC	-			V9	VCC	-		
W10	VCC	-			W10	VCC	-		
W11	VCC	-			W11	VCC	-		
W16	VCC	-			W16	VCC	-		
W17	VCC	-			W17	VCC	-		
W18	VCC	-			W18	VCC	-		
W19	VCC	-			W19	VCC	-		
W8	VCC	-			W8	VCC	-		
W9	VCC	-			W9	VCC	-		
H12	VCCIO0	0			H12	VCCIO0	0		
H13	VCCIO0	0			H13	VCCIO0	0		
J10	VCCIO0	0			J10	VCCIO0	0		
J11	VCCIO0	0			J11	VCCIO0	0		
J12	VCCIO0	0			J12	VCCIO0	0		
J13	VCCIO0	0			J13	VCCIO0	0		
H14	VCCIO1	1			H14	VCCIO1	1		
H15	VCCIO1	1			H15	VCCIO1	1		

LatticeECP Commercial

Part Number	I/Os	Grade	Package	Pins/Balls	Temp.	LUTs
LFCEP6E-3FN484C	224	-3	Lead-Free fpBGA	484	COM	6.1K
LFCEP6E-4FN484C	224	-4	Lead-Free fpBGA	484	COM	6.1K
LFCEP6E-5FN484C	224	-5	Lead-Free fpBGA	484	COM	6.1K
LFCEP6E-3FN256C	195	-3	Lead-Free fpBGA	256	COM	6.1K
LFCEP6E-4FN256C	195	-4	Lead-Free fpBGA	256	COM	6.1K
LFCEP6E-5FN256C	195	-5	Lead-Free fpBGA	256	COM	6.1K
LFCEP6E-3QN208C	147	-3	Lead-Free PQFP	208	COM	6.1K
LFCEP6E-4QN208C	147	-4	Lead-Free PQFP	208	COM	6.1K
LFCEP6E-5QN208C	147	-5	Lead-Free PQFP	208	COM	6.1K
LFCEP6E-3TN144C	97	-3	Lead-Free TQFP	144	COM	6.1K
LFCEP6E-4TN144C	97	-4	Lead-Free TQFP	144	COM	6.1K
LFCEP6E-5TN144C	97	-5	Lead-Free TQFP	144	COM	6.1K

Part Number	I/Os	Grade	Package	Pins/Balls	Temp.	LUTs
LFCEP10E-3FN484C	288	-3	Lead-Free fpBGA	484	COM	10.2K
LFCEP10E-4FN484C	288	-4	Lead-Free fpBGA	484	COM	10.2K
LFCEP10E-5FN484C	288	-5	Lead-Free fpBGA	484	COM	10.2K
LFCEP10E-3FN256C	195	-3	Lead-Free fpBGA	256	COM	10.2K
LFCEP10E-4FN256C	195	-4	Lead-Free fpBGA	256	COM	10.2K
LFCEP10E-5FN256C	195	-5	Lead-Free fpBGA	256	COM	10.2K
LFCEP10E-3QN208C	147	-3	Lead-Free PQFP	208	COM	10.2K
LFCEP10E-4QN208C	147	-4	Lead-Free PQFP	208	COM	10.2K
LFCEP10E-5QN208C	147	-5	Lead-Free PQFP	208	COM	10.2K

Part Number	I/Os	Grade	Package	Pins/Balls	Temp.	LUTs
LFCEP15E-3FN484C	352	-3	Lead-Free fpBGA	484	COM	15.3K
LFCEP15E-4FN484C	352	-4	Lead-Free fpBGA	484	COM	15.3K
LFCEP15E-5FN484C	352	-5	Lead-Free fpBGA	484	COM	15.3K
LFCEP15E-3FN256C	195	-3	Lead-Free fpBGA	256	COM	15.3K
LFCEP15E-4FN256C	195	-4	Lead-Free fpBGA	256	COM	15.3K
LFCEP15E-5FN256C	195	-5	Lead-Free fpBGA	256	COM	15.3K

Part Number	I/Os	Grade	Package	Pins/Balls	Temp.	LUTs
LFCEP20E-3FN672C	400	-3	Lead-Free fpBGA	672	COM	19.7K
LFCEP20E-4FN672C	400	-4	Lead-Free fpBGA	672	COM	19.7K
LFCEP20E-5FN672C	400	-5	Lead-Free fpBGA	672	COM	19.7K
LFCEP20E-3FN484C	400	-3	Lead-Free fpBGA	484	COM	19.7K
LFCEP20E-4FN484C	400	-4	Lead-Free fpBGA	484	COM	19.7K
LFCEP20E-5FN484C	400	-5	Lead-Free fpBGA	484	COM	19.7K

Part Number	I/Os	Grade	Package	Pins/Balls	Temp.	LUTs
LFCEP33E-3FN672C	496	-3	Lead-Free fpBGA	672	COM	32.8K
LFCEP33E-4FN672C	496	-4	Lead-Free fpBGA	672	COM	32.8K
LFCEP33E-5FN672C	496	-5	Lead-Free fpBGA	672	COM	32.8K

LatticeECP Commercial (Continued)

Part Number	I/Os	Grade	Package	Pins/Balls	Temp.	LUTs
LFECP33E-3FN484C	360	-3	Lead-Free fpBGA	484	COM	32.8K
LFECP33E-4FN484C	360	-4	Lead-Free fpBGA	484	COM	32.8K
LFECP33E-5FN484C	360	-5	Lead-Free fpBGA	484	COM	32.8K

LatticeEC Industrial

Part Number	I/Os	Grade	Package	Pins/Balls	Temp.	LUTs
LFEC1E-3QN208I	112	-3	Lead-Free PQFP	208	IND	1.5K
LFEC1E-4QN208I	112	-4	Lead-Free PQFP	208	IND	1.5K
LFEC1E-3TN144I	97	-3	Lead-Free TQFP	144	IND	1.5K
LFEC1E-4TN144I	97	-4	Lead-Free TQFP	144	IND	1.5K
LFEC1E-3TN100I	67	-3	Lead-Free TQFP	100	IND	1.5K
LFEC1E-4TN100I	67	-4	Lead-Free TQFP	100	IND	1.5K

Part Number	I/Os	Grade	Package	Pins/Balls	Temp.	LUTs
LFEC3E-3FN256I	160	-3	Lead-Free fpBGA	256	IND	3.1K
LFEC3E-4FN256I	160	-4	Lead-Free fpBGA	256	IND	3.1K
LFEC3E-3QN208I	145	-3	Lead-Free PQFP	208	IND	3.1K
LFEC3E-4QN208I	145	-4	Lead-Free PQFP	208	IND	3.1K
LFEC3E-3TN144I	97	-3	Lead-Free TQFP	144	IND	3.1K
LFEC3E-4TN144I	97	-4	Lead-Free TQFP	144	IND	3.1K
LFEC3E-3TN100I	67	-3	Lead-Free TQFP	100	IND	3.1K
LFEC3E-4TN100I	67	-4	Lead-Free TQFP	100	IND	3.1K

Part Number	I/Os	Grade	Package	Pins/Balls	Temp.	LUTs
LFEC6E-3FN484I	224	-3	Lead-Free fpBGA	484	IND	6.1K
LFEC6E-4FN484I	224	-4	Lead-Free fpBGA	484	IND	6.1K
LFEC6E-3FN256I	195	-3	Lead-Free fpBGA	256	IND	6.1K
LFEC6E-4FN256I	195	-4	Lead-Free fpBGA	256	IND	6.1K
LFEC6E-3QN208I	147	-3	Lead-Free PQFP	208	IND	6.1K
LFEC6E-4QN208I	147	-4	Lead-Free PQFP	208	IND	6.1K
LFEC6E-3TN144I	97	-3	Lead-Free TQFP	144	IND	6.1K
LFEC6E-4TN144I	97	-4	Lead-Free TQFP	144	IND	6.1K

Part Number	I/Os	Grade	Package	Pins/Balls	Temp.	LUTs
LFEC10E-3FN484I	288	-3	Lead-Free fpBGA	484	IND	10.2K
LFEC10E-4FN484I	288	-4	Lead-Free fpBGA	484	IND	10.2K
LFEC10E-3FN256I	195	-3	Lead-Free fpBGA	256	IND	10.2K
LFEC10E-4FN256I	195	-4	Lead-Free fpBGA	256	IND	10.2K
LFEC10E-3QN208I	147	-3	Lead-Free PQFP	208	IND	10.2K
LFEC10E-4QN208I	147	-4	Lead-Free PQFP	208	IND	10.2K